PHY Channels based on Class II, with new Bel ARJ45 MDI and variances of PCBs

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Introduction

- At the last Channel ad hoc February 18 a new MDI including magnetics was presented. The electrical performance is on a high level and it is to be seen how it performs with cablings and PCBs.
- It is based on ARJ45 connectivity

From Indian Wells Presentation

franck_3bq_01a_0114

- The published S16P files for different parts of the PHY channel are read into a program which calculates for two pairs the corresponding 8x8 M-matrix (mixed mode) for each component.
- These matrices are transformed into chain T-matrices which can be multiplied meaning the components are concatenated.
- After transforming back the transmission values of the concatenation are obtained.
- All pair combinations from both sides with all values (dd,cc, cd) can be calculated, but to get a better overview only two pairs at a time for dd are presented.
- If necessary he result can be exported to CSV for all parameters.

Characteristics of Bel ARJ45 and BEL RJ45 MDI



- Difference between pair were minor for the new MDI
- All values from the new MDI were checked for directivity differences, none observed.
- Therefore only one T- Matrix is sufficient to be used for both ends.

Examples of different PCBs



3 pairs like presented ones in NEXT and FEXT, 3 pair combinations much better

Examples of different ISO/IEC Class II channels

FEXT

1000

MHz

2000



50

0

1000

MHz

2000



2-26-2 m Leoni 12/13



3-24-3 m NEXANS Nexans GG45_1800



similar at all pair combinations different pachcord length two presented at Indian Wells franck_3bq_01c_0114

2000

100

0

1000

MHz

40

0

1000

MHz

IEEE 802.3bq Channel ad hoc March 4 2014

2000

100

0

1000

MHz

2000

PHY channel with new Bel MDI

(30m Leoni)



Set up:

PCB
100-8-25
Bel ARJ45
Inc. magnetics
Cabling Channel
30m Leoni
Bel ARJ45
Inc. magnetics
PCB
100-8-25

As Common mode rejection ratio was asked for at last channel ad hoc it is shown here (blue curve) together with TCL and TCTL. Other pairs similar.

Comparison PHY channel with old and new Bel MDI #1



Leoni 30m, PCB 100-8-25

Comparison PHY channel with old and new Bel MDI #2



Nexans 30m, PCB 100-8-25 Panduit similar

- As this 8.2 cabling channels presented do not show major differences the only variability is the PCB layout were we have plenty proposals.
- Only the 100 Ohm PCBs will be discussed

Calculation of PHY channels with new MDI and different PCB layouts #1



30m Leoni, results for NEXANS and Panduit look similar

Calculation of PHY channels with new MDI and different PCB layouts #2



30m Leoni, results for NEXANS and Panduit look similar

Summary and Recommendations

 PHY Channel based on Class II cabling (Non RJ45) with new Bel ARJ45 MDI show much more margin in NEXT and FEXT compared to PHY Channel based Class I cabling (RJ45).

– Class I see Indian Wells franck_3bq_01c_0114

 IL and RL are still "bad" for frequencies above 1.600 MHz

Summary and Recommendations

• Recommendations for the PCB:

- For NEXT a minimum of 25 mil separation is recommended, especially for long PCBs, as NEXT is mostly set at the beginning of channels. As only 3 pair combinations are critical it should be viable to think about a crossing halfway if long lines are needed.
 - If 15 mil separation is chosen Channel NEXT is PCB limited and about 12 dB worse.
- FEXT is not so depending on PCB length and separation because it adds to the rest of the channel.
- Return loss for 100 Ohm PCB can be neglected, should the non 100 Ohm cases be investigated?
- For IL up to 1600 MHz there is around 1 dB increase from 3 to 8 inches but as discussed this value is under discussion depending on PCB material.

Shielding

- In the last channel adhoc a question was raised if it is sufficient to get good EMC performance with shielded systems because it may be very dependent on installation.
 - ISO IEC has two standards on installation practices for shielded and unshielded cablings with good explanations (ISO/IEC 14763-2)
 - For stable EMC performance a standard on bonding is under development (ISO/IEC 30129 CD stage)